

HETERO JUNCTION FIELD EFFECT TRANSISTOR

NE3508M04

L TO S BAND LOW NOISE AMPLIFIER N-CHANNEL HJ-FET

FEATURES

- Super low noise figure and high associated gain
 NF = 0.45 dB TYP., Ga = 14 dB TYP. @ f = 2 GHz, VDS = 2 V, ID = 10 mA
- Flat-lead 4-pin thin-type super minimold (M04) package

APPLICATIONS

- · Satellite radio (SDARS, DMB, etc.) antenna LNA
- · Low noise amplifier for microwave communication system

ORDERING INFORMATION

| Part Number | Order Number | Package | Quantity | Marking | Supplying Form |
|---------------|-----------------|-------------------------------------|-------------------|---------|---|
| NE3508M04 | NE3508M04-A | Flat-lead 4-pin thin- | 50 pcs (Non reel) | V79 | 8 mm wide embossed taping |
| NE3508M04-T2 | NE3508M04-T2-A | type super minimold (M04) (Pb-Free) | 3 kpcs/reel | | Pin 1 (Source), Pin 2 (Drain) face the perforation side of the tape |
| NE3508M04-T2B | NE3508M04-T2B-A | ` '\ ' | 15 kpcs/reel | | the perioration side of the tape |

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Remark To order evaluation samples, contact your nearby sales office.

Part number for sample order: NE3508M04

ABSOLUTE MAXIMUM RATINGS ($T_A = +25^{\circ}C$)

| Parameter | Symbol | Ratings | Unit |
|-------------------------|------------------|-------------|------|
| Drain to Source Voltage | V _{DS} | 4.0 | V |
| Gate to Source Voltage | V _{GS} | -3.0 | V |
| Drain Current | lο | IDSS | mA |
| Gate Current | lg | 400 | μΑ |
| Total Power Dissipation | Ptot Note | 175 | mW |
| Channel Temperature | Tch | +150 | °C |
| Storage Temperature | T _{stg} | -65 to +150 | °C |

Note Mounted on 1.08 cm² × 1.0 mm (t) glass epoxy PCB

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version. Not all products and/or types are available in every country. Please check with an NEC Electronics sales representative for availability and additional information.

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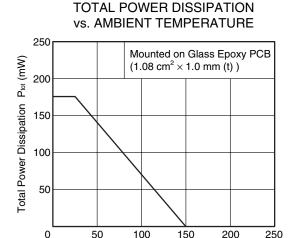
RECOMMENDED OPERATING CONDITIONS (Ta = +25°C)

| Parameter | Symbol | MIN. | TYP. | MAX. | Unit |
|-------------------------|-----------------|------|------|------|------|
| Drain to Source Voltage | V _{DS} | - | 2 | 3 | V |
| Drain Current | lσ | - | 10 | 30 | mA |
| Input Power | Pin | _ | _ | 0 | dBm |

ELECTRICAL CHARACTERISTICS (T_A = +25°C, unless otherwise specified)

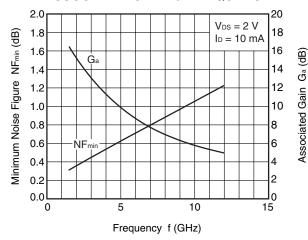
| Parameter | Symbol | Test Conditions | MIN. | TYP. | MAX. | Unit |
|-------------------------------|------------|--|-------|------|-------|------|
| Gate to Source Leak Current | Igso | V _{GS} = -3 V | ı | 1 | 20 | μΑ |
| Saturated Drain Current | IDSS | V _{DS} = 2 V, V _{GS} = 0 V | 60 | 90 | 120 | mA |
| Gate to Source Cutoff Voltage | VGS (off) | $V_{DS} = 2 \text{ V}, I_{D} = 100 \ \mu\text{A}$ | -0.25 | -0.5 | -0.75 | V |
| Transconductance | g m | V _{DS} = 2 V, I _D = 10 mA | 100 | _ | _ | mS |
| Noise Figure | NF | V _{DS} = 2 V, I _D = 10 mA, f = 2 GHz | - | 0.45 | 0.7 | dB |
| Associated Gain | Ga | | 12 | 14 | - | dB |
| Gain 1 dB Compression | Po (1 dB) | V _{DS} = 3 V, I _D = 30 mA (Non-RF), | _ | 18 | _ | dBm |
| Output Power | | f = 2 GHz | | | | |

TYPICAL CHARACTERISTICS (TA = +25°C, unless otherwise specified)

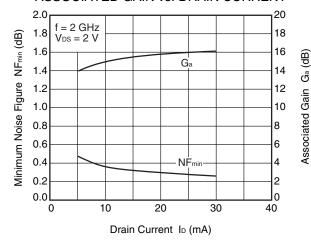


MINIMUM NOISE FIGURE, ASSOCIATED GAIN vs. FREQUENCY

Ambient Temperature TA (°C)

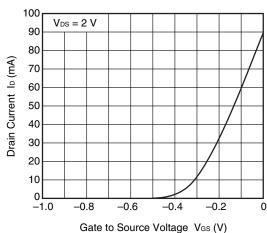


MINIMUM NOISE FIGURE, ASSOCIATED GAIN vs. DRAIN CURRENT

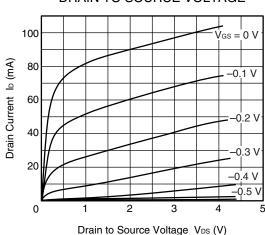


Remark The graphs indicate nominal characteristics.

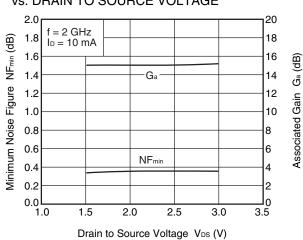
DRAIN CURRENT vs. GATE TO SOURCE VOLTAGE



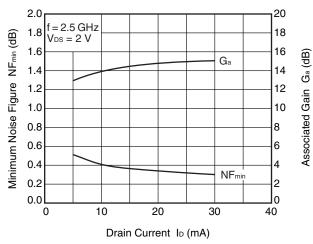
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



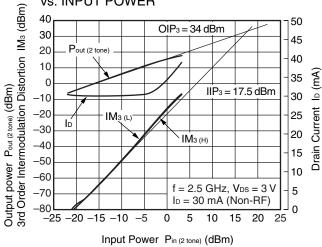
MINIMUM NOISE FIGURE, ASSOCIATED GAIN vs. DRAIN TO SOURCE VOLTAGE



MINIMUM NOISE FIGURE, ASSOCIATED GAIN vs. DRAIN CURRENT

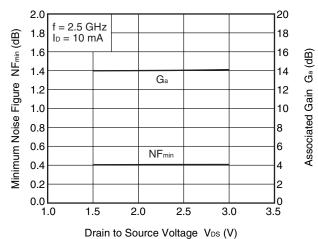


OUTPUT POWER, IM3, DRAIN CURRENT vs. INPUT POWER



Remark The graphs indicate nominal characteristics.

MINIMUM NOISE FIGURE, ASSOCIATED GAIN vs. DRAIN TO SOURCE VOLTAGE



S-PARAMETERS

S-parameters and noise parameters are provided on our Web site in a format (S2P) that enables the direct import of the parameters to microwave circuit simulators without the need for keyboard inputs.

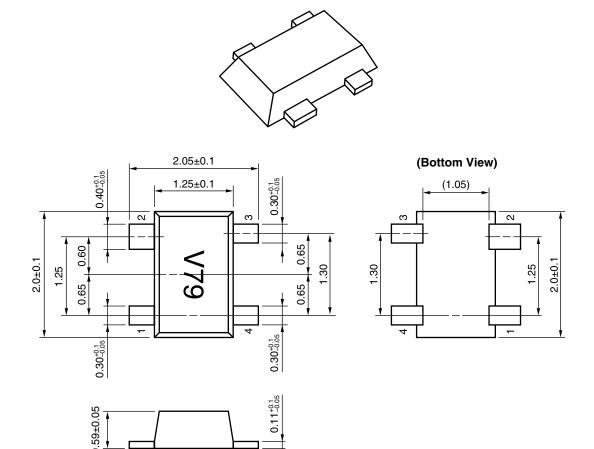
Click here to download S-parameters.

 $[\mathsf{RF} \ \mathsf{and} \ \mathsf{Microwave}] \to [\mathsf{Device} \ \mathsf{Parameters}]$

URL http://www.necel.com/microwave/en/

PACKAGE DIMENSIONS

FLAT-LEAD 4-PIN THIN-TYPE SUPER MINIMOLD (M04) (UNIT: mm)

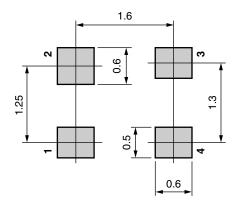


PIN CONNECTIONS

- 1. Source
- 2. Drain
- 3. Source
- 4. Gate

MOUNTING PAD DIMENSIONS (REFERENCE ONLY)

FLAT-LEAD 4-PIN THIN-TYPE SUPER MINIMOLD (M04) (UNIT: mm)



RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

| Soldering Method | Soldering Conditions | | Condition Symbol |
|------------------|---|---|------------------|
| Infrared Reflow | Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass) | : 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below | IR260 |
| Partial Heating | Peak temperature (terminal temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass) | : 350°C or below : 3 seconds or less : 0.2%(Wt.) or below | HS350 |

Caution Do not use different soldering methods together (except for partial heating).

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M8E 02.11-1

NEC NE3508M04

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GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
- Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.